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(12) **United States Design Patent**
Hara

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(54) **SEMICONDUCTOR MODULE**

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(51) **LOC (14) Cl.** **13-03**

(52) **U.S. Cl.**
USPC **D13/182**

(58) **Field of Classification Search**

USPC D13/123, 133, 146, 147, 158, 182, 184,
D13/199

(Continued)

(56) **References Cited**

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Primary Examiner — Shawn T Gingrich

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Mueller & Larson, P.C.

(57) **CLAIM**

The ornamental design for a semiconductor module, as shown and described.

DESCRIPTION

FIG. 1 is a front, top and right side perspective view of an embodiment of a semiconductor module showing my new design;

FIG. 2 is a rear, bottom and left side perspective view thereof;

FIG. 3 is a front view thereof;

FIG. 4 is a rear view thereof;

FIG. 5 is a top plan view thereof;

FIG. 6 is a bottom plan view thereof;

FIG. 7 is a right side view thereof, the left side view being a mirror image of FIG. 7;

FIG. 8 is a front, top and right side perspective view of another embodiment of a semiconductor module showing my new design;

FIG. 9 is a rear, bottom and left side perspective view thereof;

FIG. 10 is a front view thereof;

FIG. 11 is a rear view thereof;

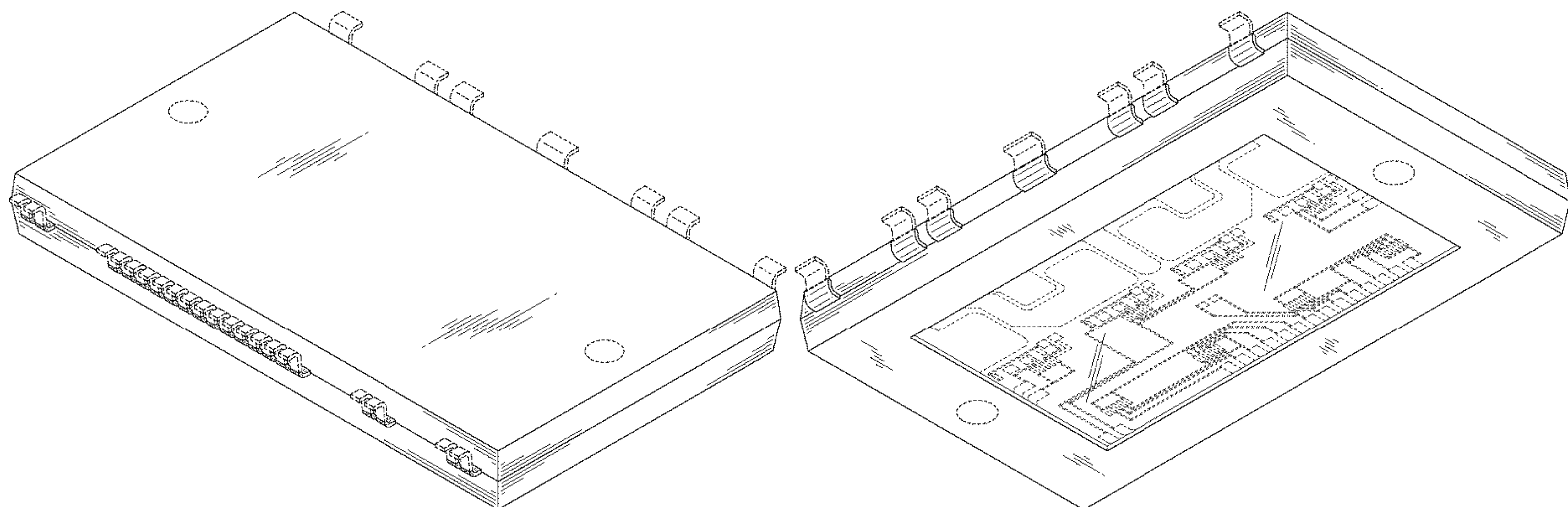
FIG. 12 is a top plan view thereof;

FIG. 13 is a bottom plan view thereof; and,

FIG. 14 is a right side view thereof, the left side view being a mirror image of FIG. 14.

The broken lines illustrate portions of the semiconductor module that form no part of the claimed design. The dash-dotted lines denote the boundary of the claim and form no part of the claimed design. The oblique line shading shown in the drawings indicates transparent parts.

1 Claim, 14 Drawing Sheets



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(58) Field of Classification Search

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 7/00; H01L 25/07; H01L 25/16; H01L
 25/18; H01L 23/00; H01L 23/31

See application file for complete search history.

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FIG.1

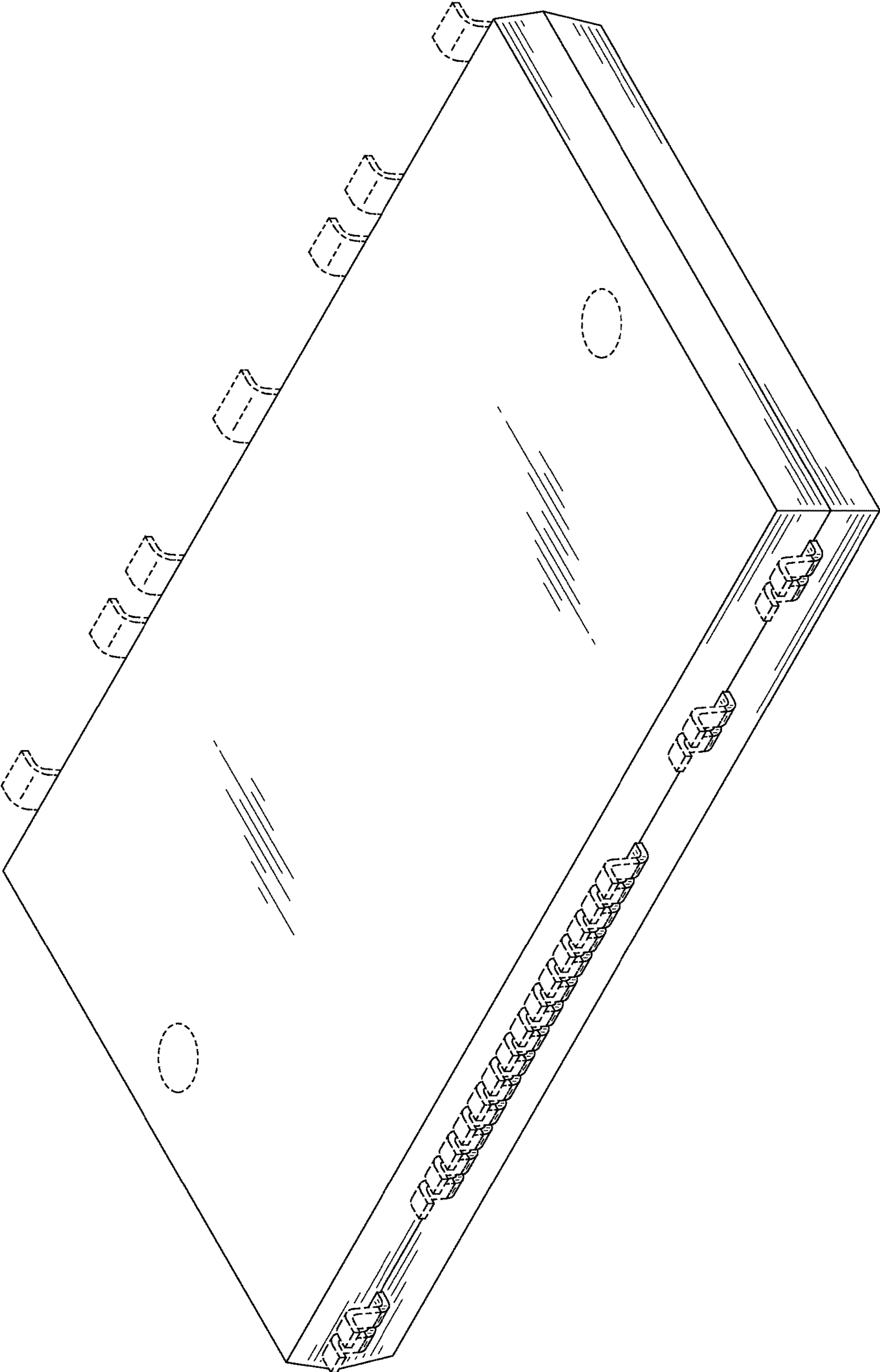


FIG.2

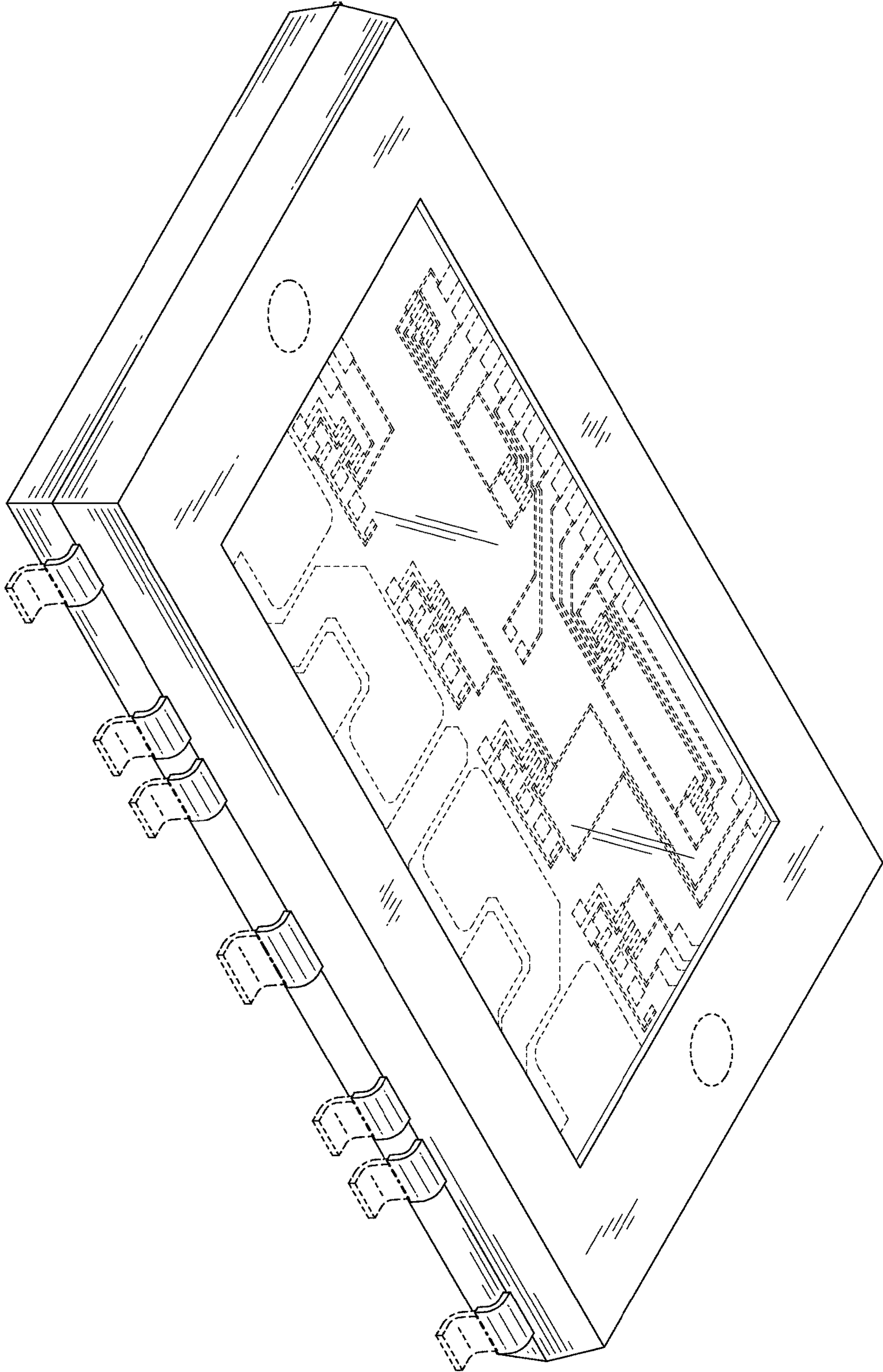


FIG. 3

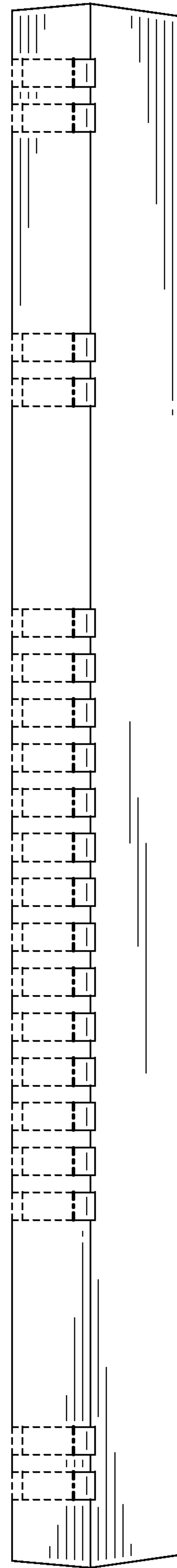


FIG.4

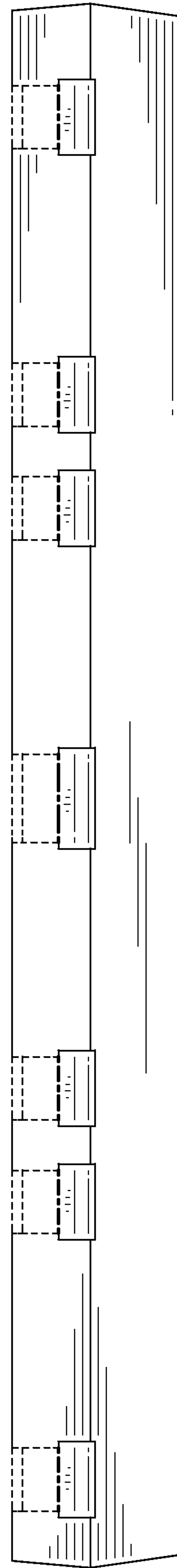
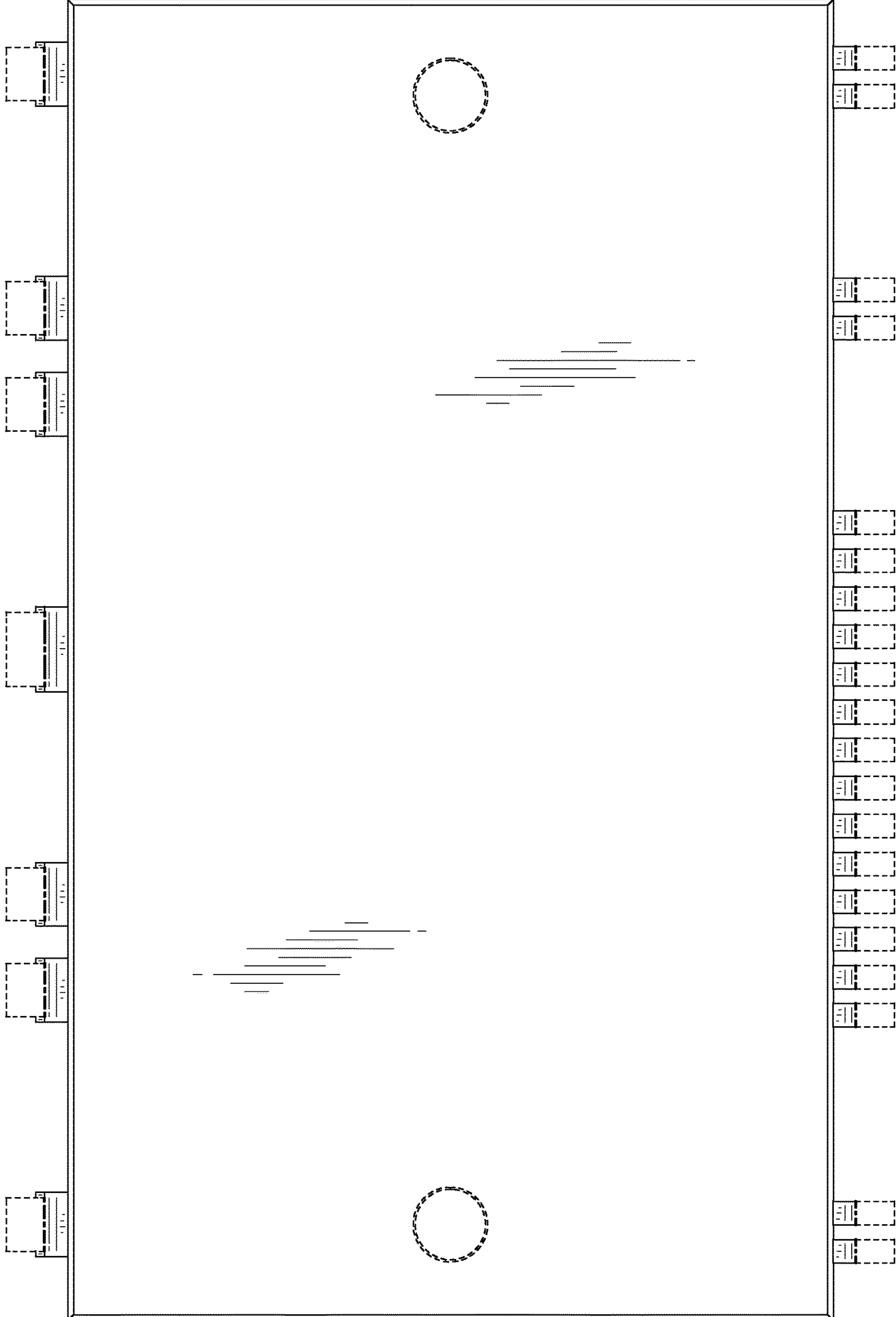


FIG.5



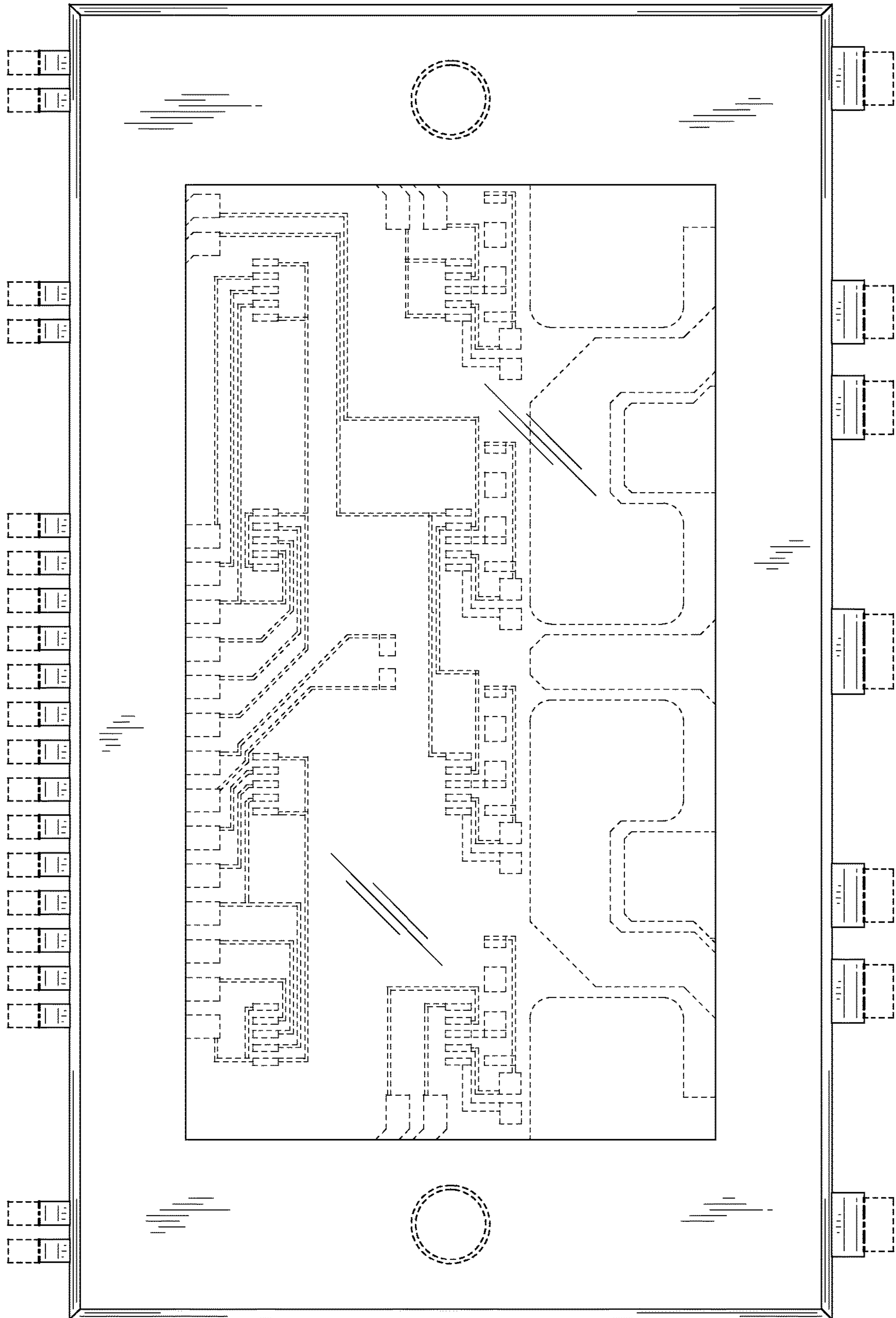


FIG. 6

FIG. 7

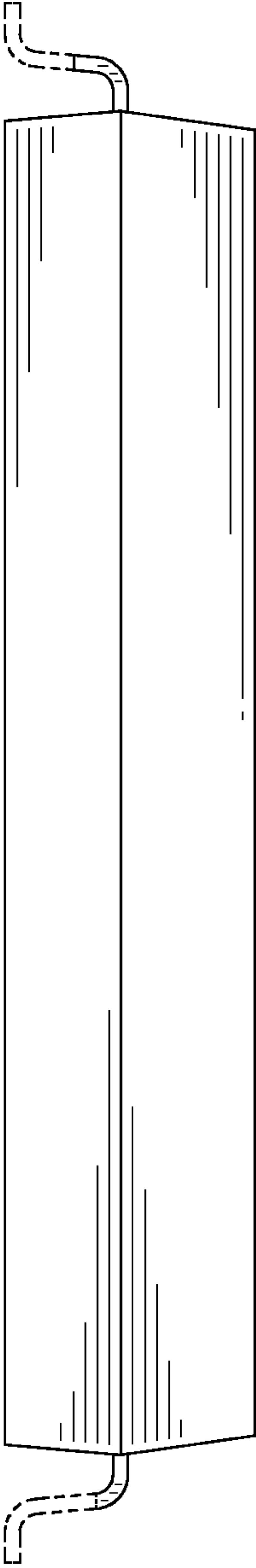


FIG. 8

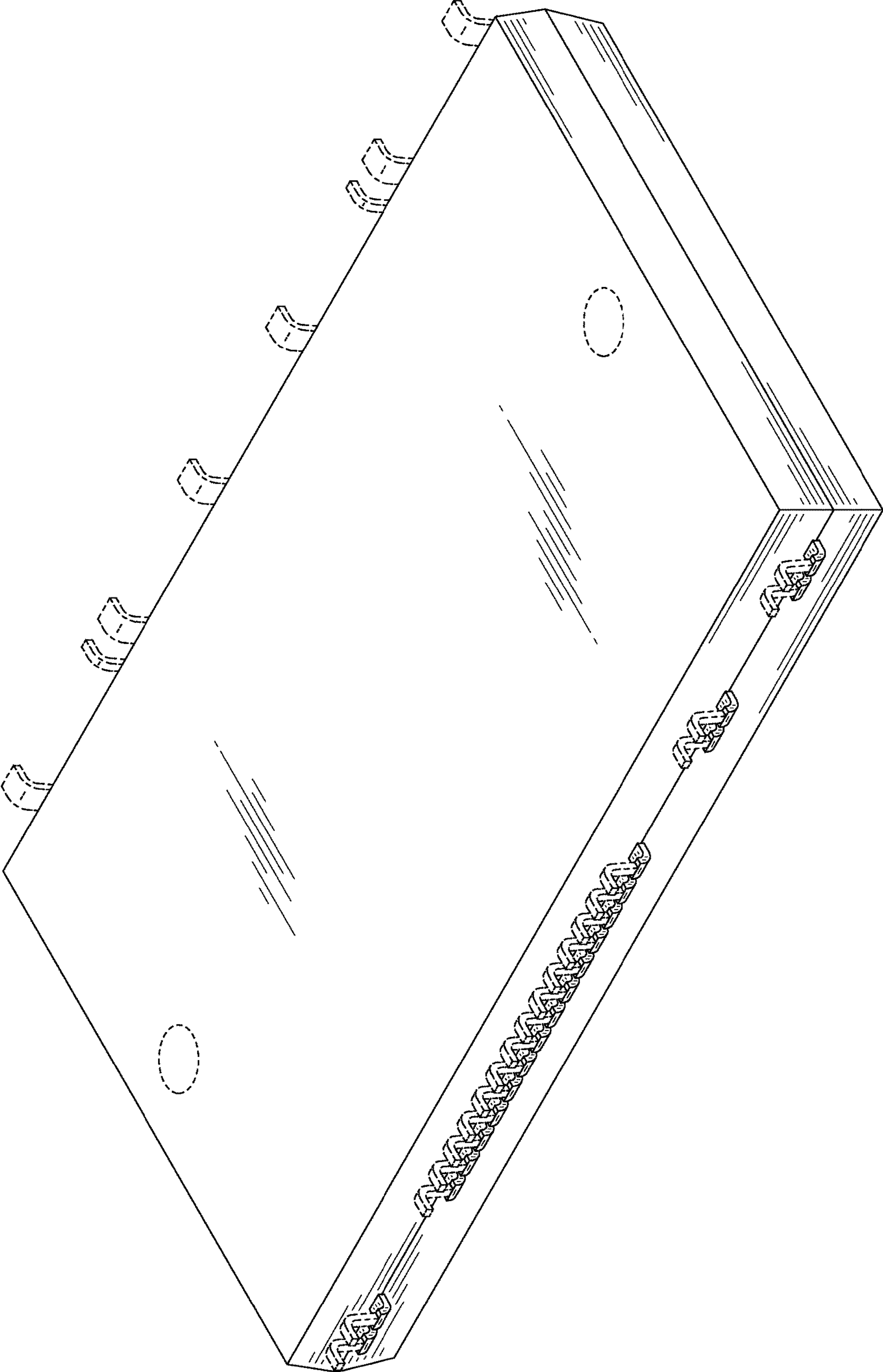


FIG. 9

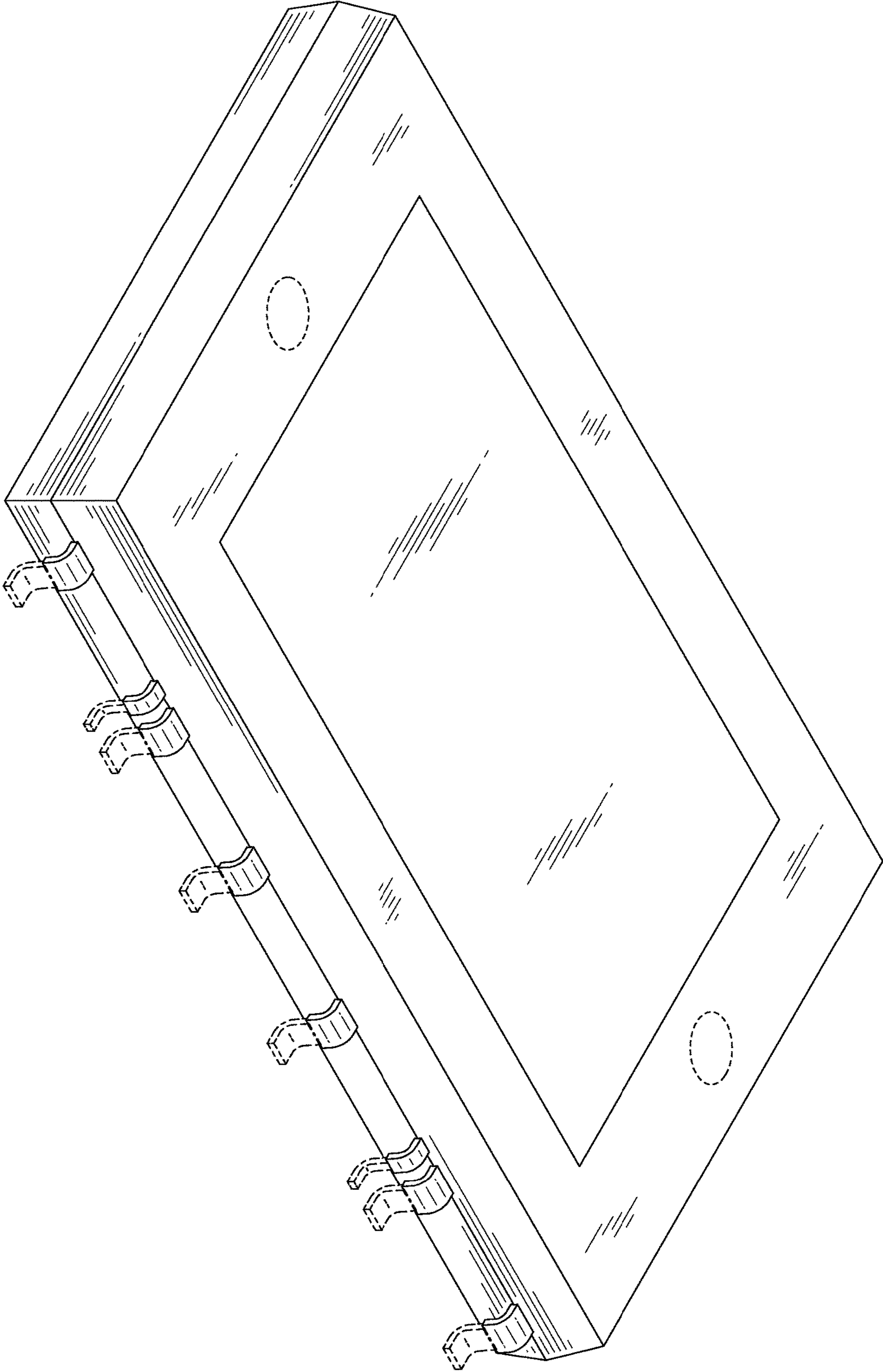


FIG.10

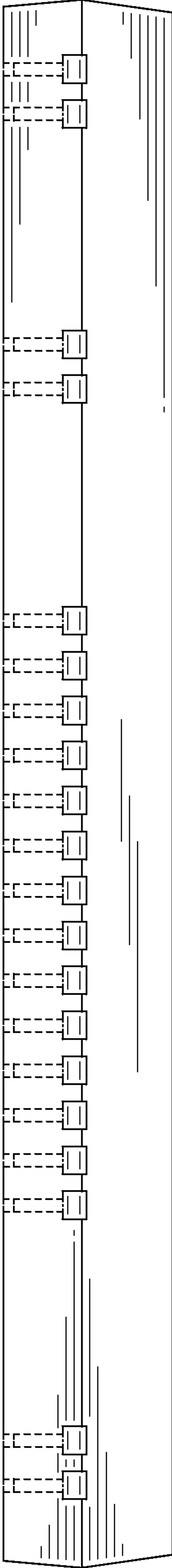


FIG.11

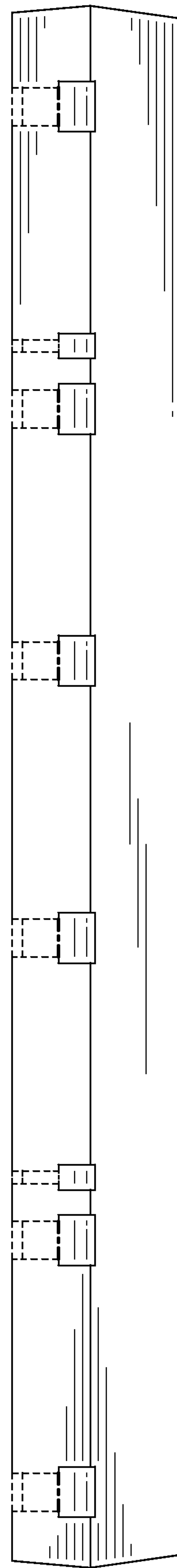
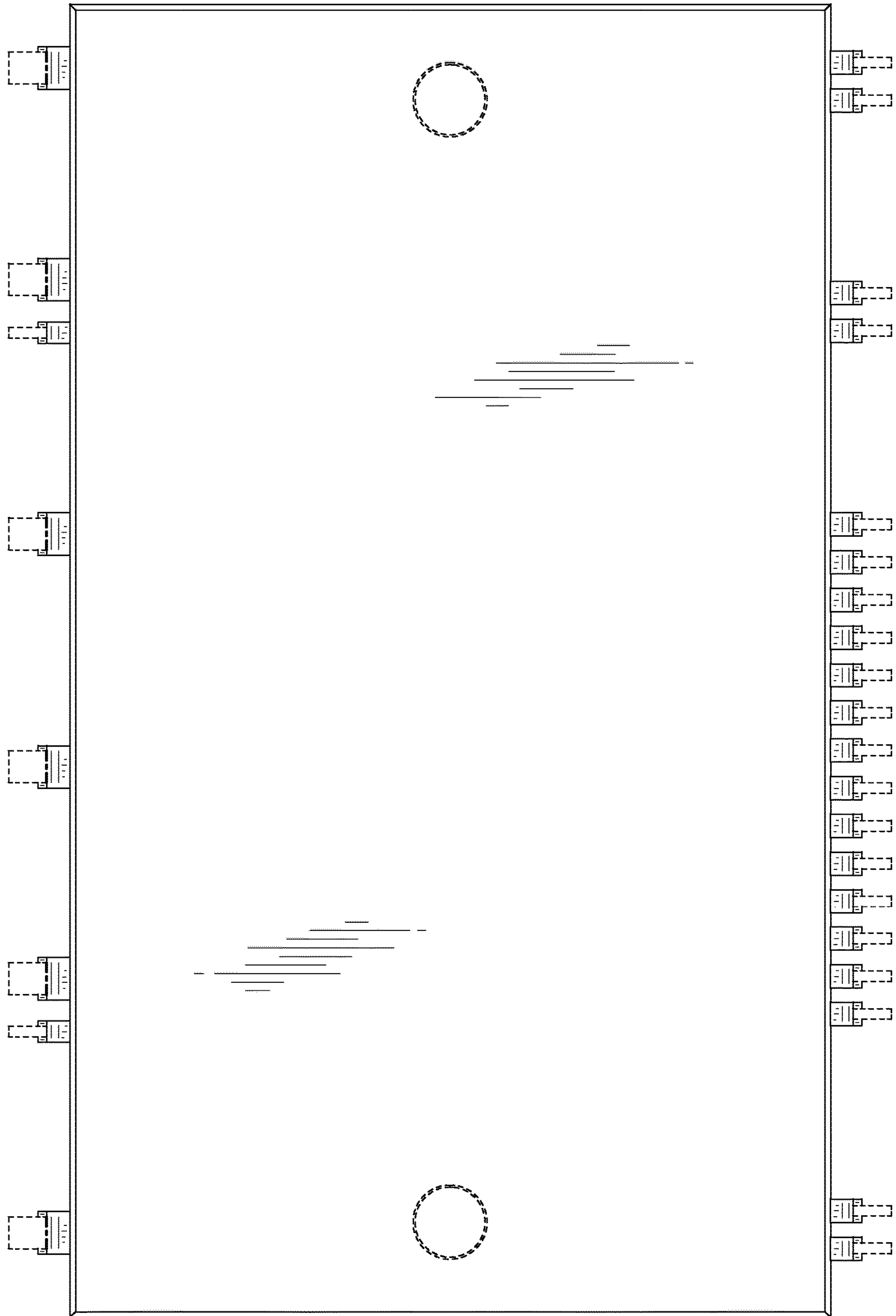


FIG. 12



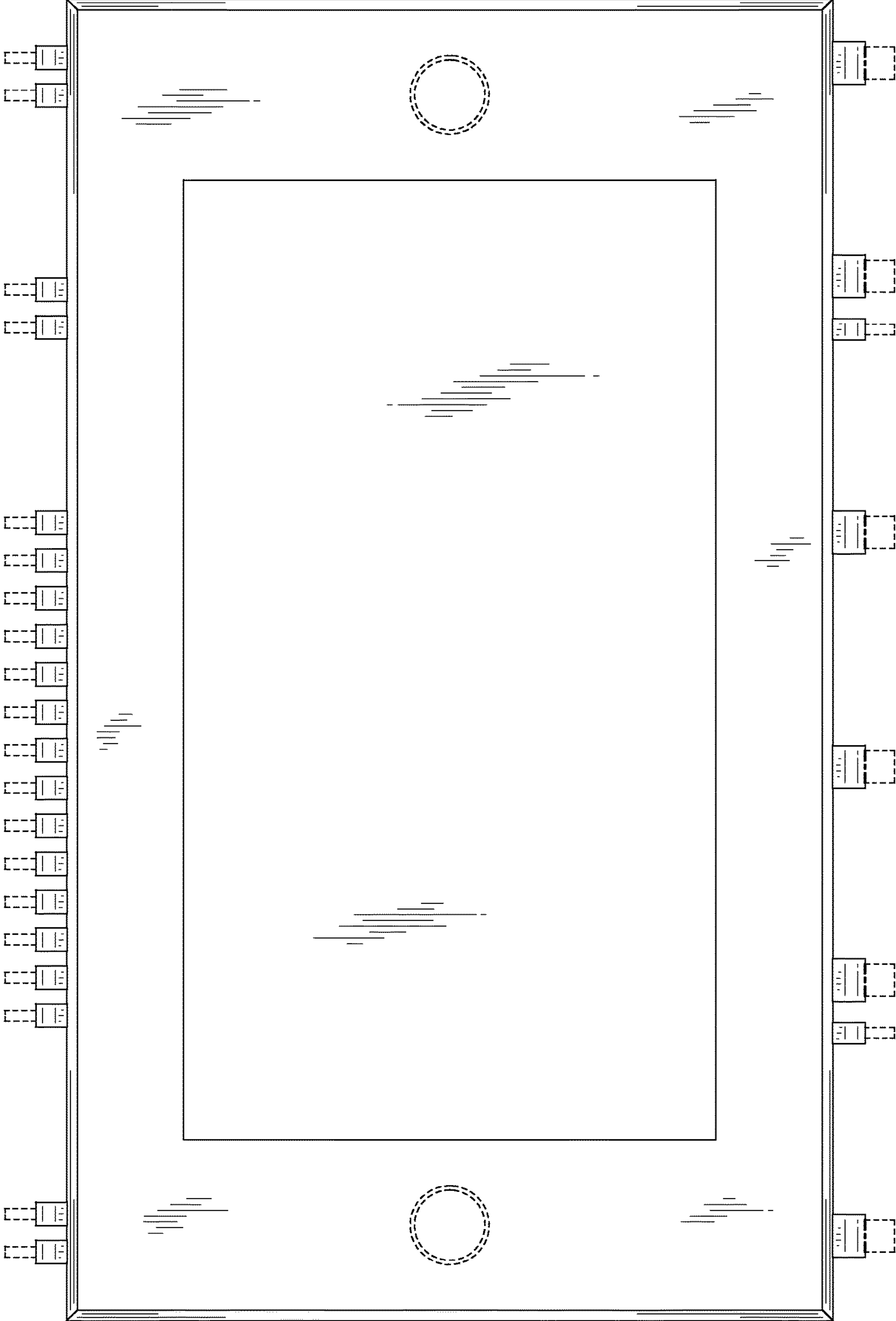


FIG. 13

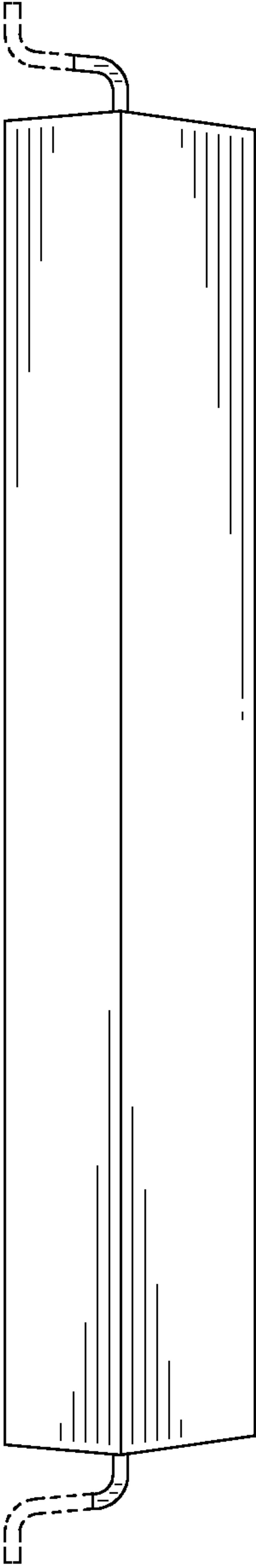


FIG.14